

ABSTRACT

The present invention provides a resin composition that contains copper particles and a particular resin and that is capable of producing a cured product having a low volume resistance value, and a cured product obtained by curing the resin composition. The resin composition contains (A) copper particles having an average particle diameter of 0.1 to 20 μm , (B) a phosphoric acid-modified epoxy resin obtained by reacting a phosphoric acid (b1) with an epoxy compound (b2), and (C) a curing agent, wherein the content of the component (B) and the content of the component (C), based on 100 parts by mass of the total amount of the components (A) to (C), are 0.1 to 30 parts by mass and 0.1 to 5 parts by mass, respectively. Further, the cured product is obtained by curing the resin composition.